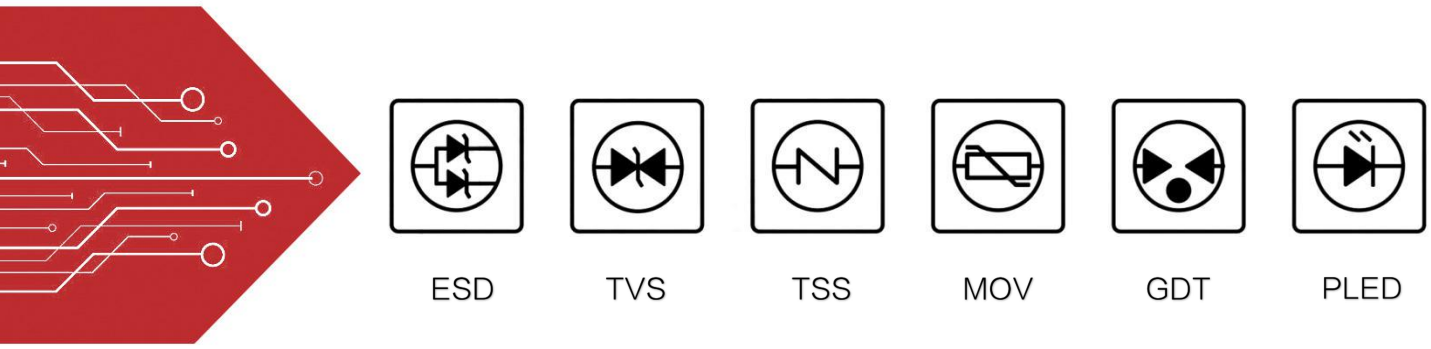
MSKSEMI
SEMICONDUCTOR



Product data sheet

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SOD-123FL

FEATURES

* Ideal for surface mount applications
* Easy pick and place
* Built-in strain relief
* Low forward voltage drop

MECHANICAL DATA

* Case: Molded plastic
* Epoxy: UL 94V-0 rate flame retardant
* Metallurgically bonded construction
* Polarity: Color band denotes cathode end
* Mounting position: Any

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25˚C ambient temperature uniess otherwies specified.
Single phase half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

	P/N	DS32W-MS	DS33W-MS	DS34W-MS	DS35W-MS	DS36W-MS	DS38W-MS	DS39W-MS	DS310W-MS	
TYPE NUMBER	MARK	K32	K33	K34	K35	K36	K38	K39	K310	UNITS
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	20	30	40	50	60	80	90	100	V
Maximum RMS Voltage	V_{RMS}	14	21	28	35	42	56	63	70	V
Maximum DC Blocking Voltage	V_{DC}	20	30	40	50	60	80	90	100	V
Maximum Average Forward Rectified Current At T_L=100˚C	$I_{(AV)}$	3.0								A
Peak Forward Surge Current, 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)	I_{FSM}	80								A
Maximum Instantaneous Forward Voltage at 3.0A	V_F	0.55			0.70		0.85			V
Maximum DC Reverse Current Ta=25˚C	I_R	0.1					0.02			mA
at Rated DC Blocking Voltage Ta=100˚C		5					2			mA
Operating Temperature Range T_J	T_J	-65 — +150								˚C
Storage Temperature Range T_{STG}	T_{STG}	-65 — +150								˚C

NOTES:

1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.

2. Thermal Resistance Junction to Lead.

RATING AND CHARACTERISTIC CURVES (K32 THRU K310)

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

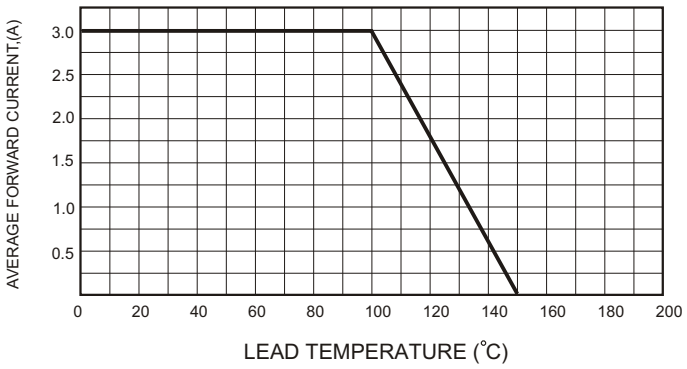


FIG.2-TYPICAL FORWARD CHARACTERISTICS

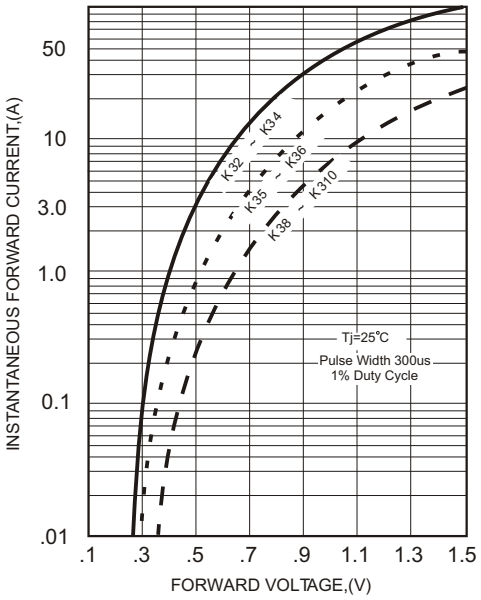


FIG.3-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

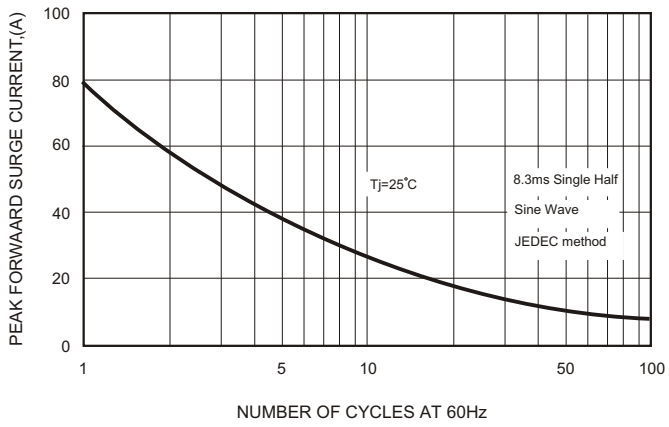


FIG.4-TYPICAL JUNCTION CAPACITANCE

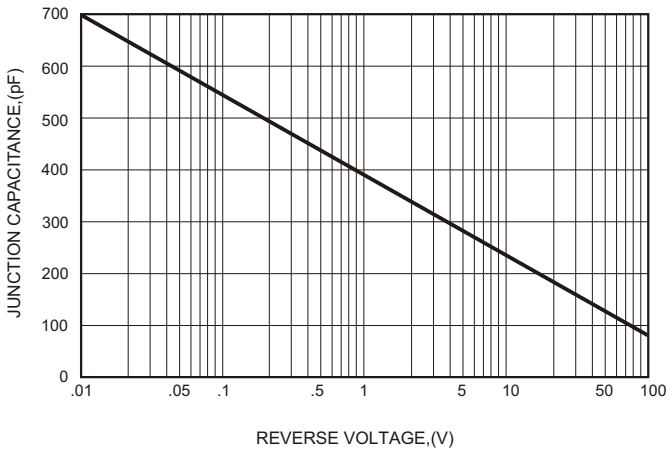
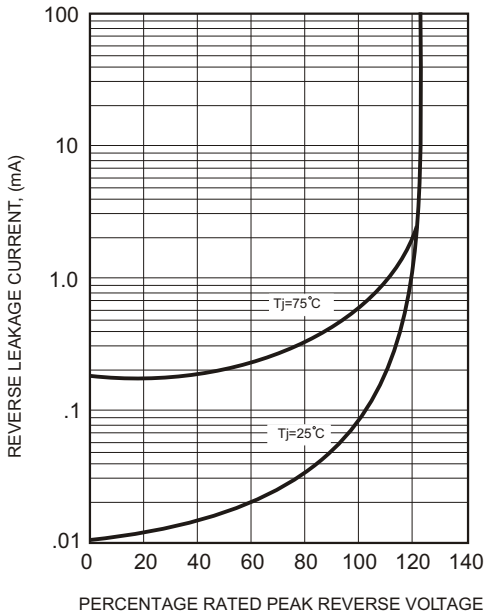
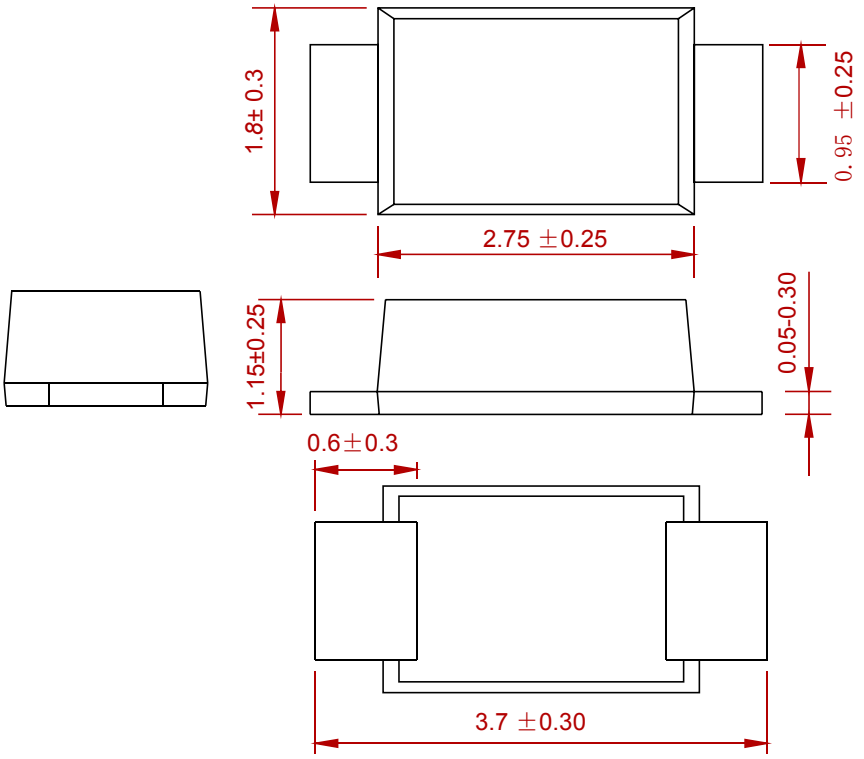


FIG.5 - TYPICAL REVERSE CHARACTERISTICS

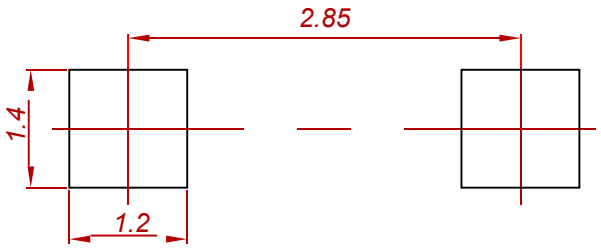


PACKAGE MECHANICAL DATA



Dimensions in millimeters

Suggested Pad Layout



Note:
1.Controlling dimension:in millimeters.
2.General tolerance:± 0.05mm.
3.The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
DS32W-MS THRU DS310W-MS	SOD-123FL	3000

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